APPARATUS AND METHOD FOR EVENLY FLOWING PROCESSING GAS ONTO A SEMICONDUCTOR WAFER

Abstract of the Disclosure

A semiconductor processing apparatus with a chamber,

a wafer holder and a processing gas inlet pipe is
provided with an impeller fixed within the inlet pipe.

As gas flows through slots in the impeller, the gas is
directed into a plurality of generally horizontal streams
beneath the impeller which cause a swirling whirlpoollike motion of the gas in a lower portion of the pipe.

As the swirling gas flows out of an exit-end of the pipe,
centrifugal forces cause the gas immediately to flow
outward within the chamber so that on passing down onto a
wafer the gas flows uniformly across a surface of the

wafer.